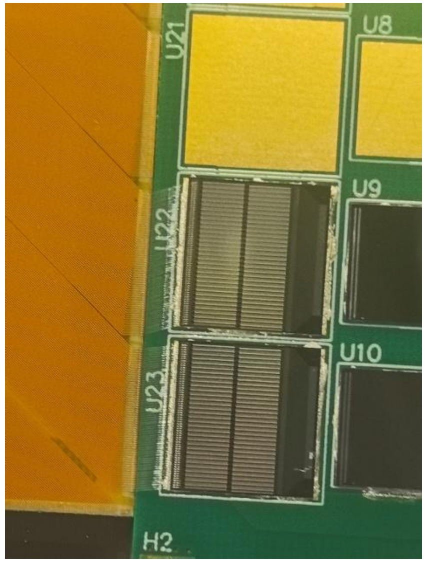
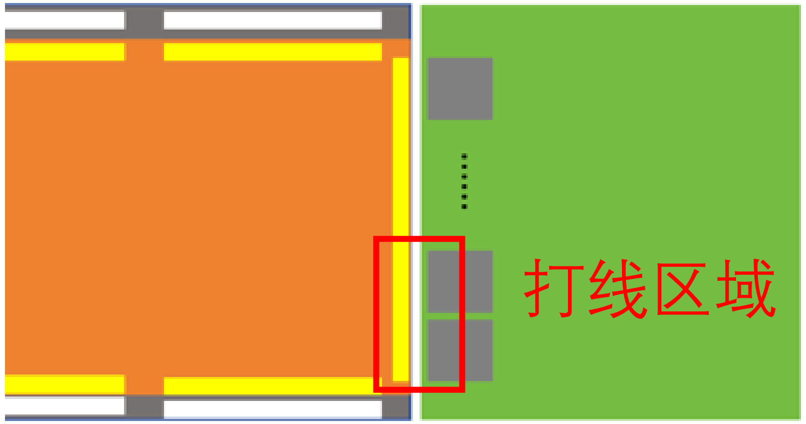
HERD STK/SCD group meeting

实验物理中心
金梁程龙
2026.01.16

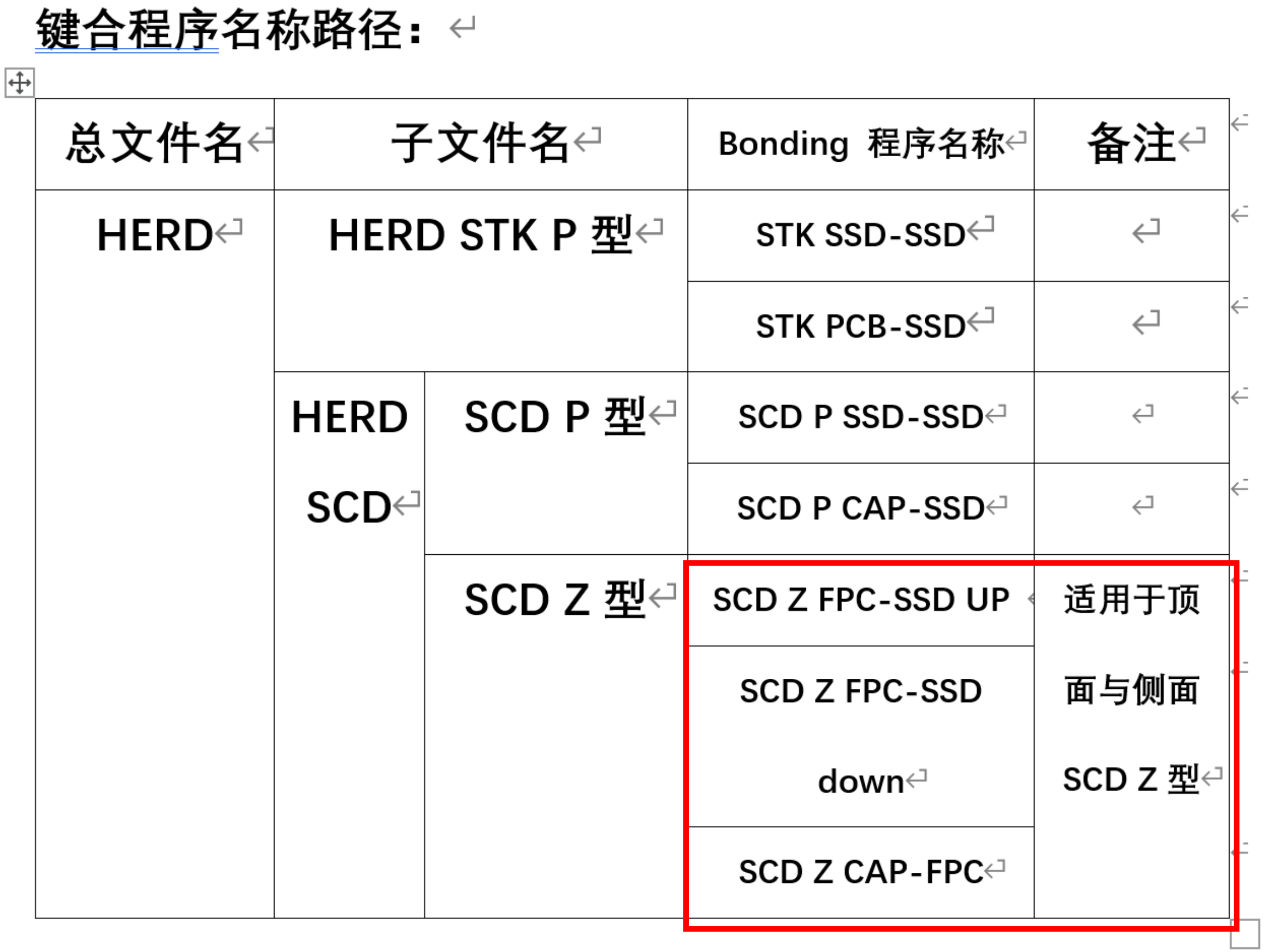
SCD Z 型CAP – FPC 打线





- 基于当前SCD Z型 dummy ladder，编写完成HERD CAP-SSD wire bonding程序，初步优化了键合参数
- 已完成#8 #9区域CAP-FPC之间bonding（128根线，一次成功）
- FPC 边缘处处于悬空状态，少胶
- 下一步等待第一条完整SCD Z型dummy ladder 贴片完成，进行打线

◘HERD STK/SCD bonding技术文档

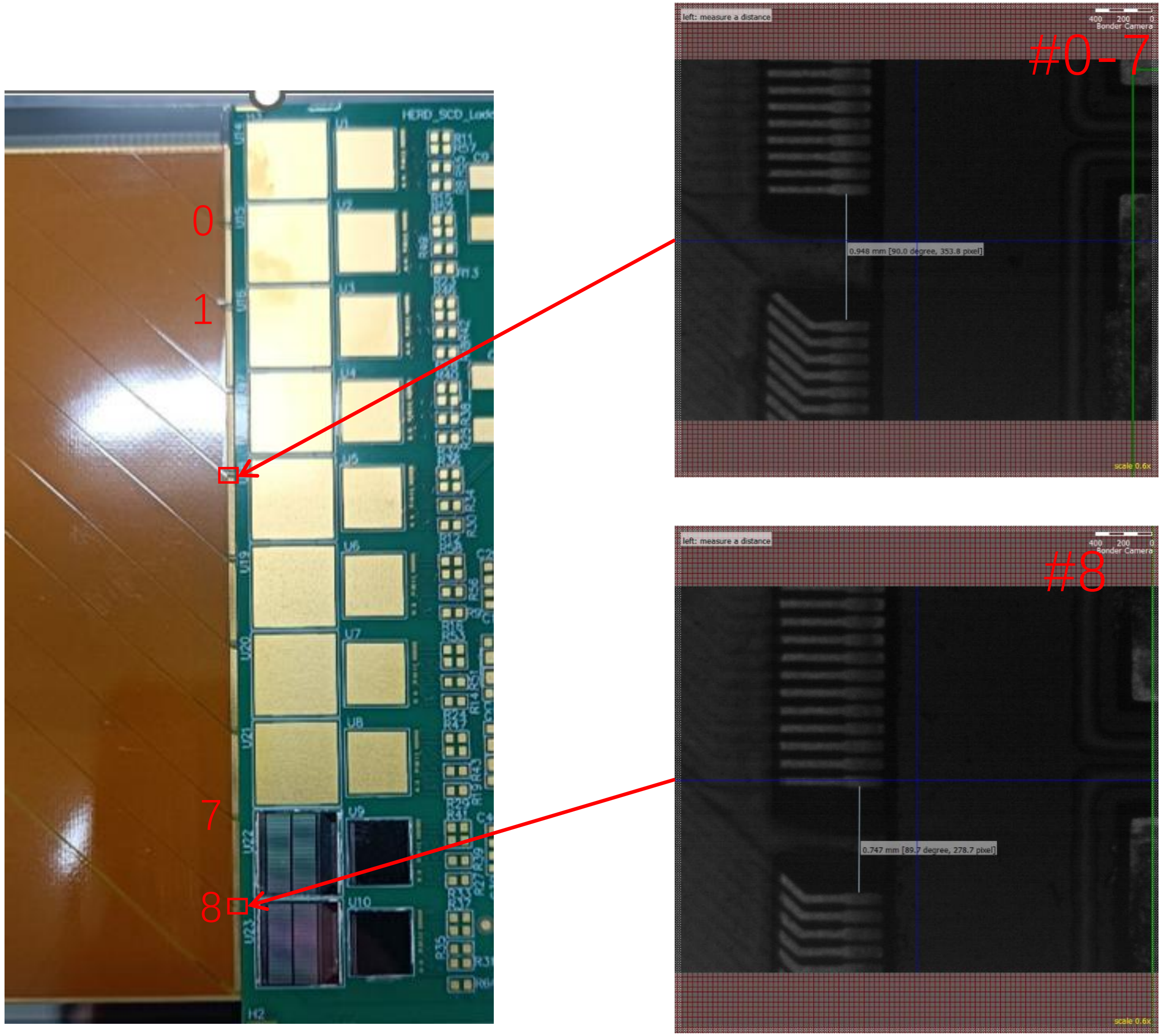


键合程序名称路径：

总文件名	子文件名		Bonding 程序名称	备注
HERD	HERD STK P 型		STK SSD-SSD	
			STK PCB-SSD	
	HERD SCD	SCD P 型	SCD P SSD-SSD	
			SCD P CAP-SSD	
		SCD Z 型	SCD Z FPC-SSD UP	适用于顶面与侧面SCD Z 型
			SCD Z FPC-SSD down	
			SCD Z CAP-FPC	

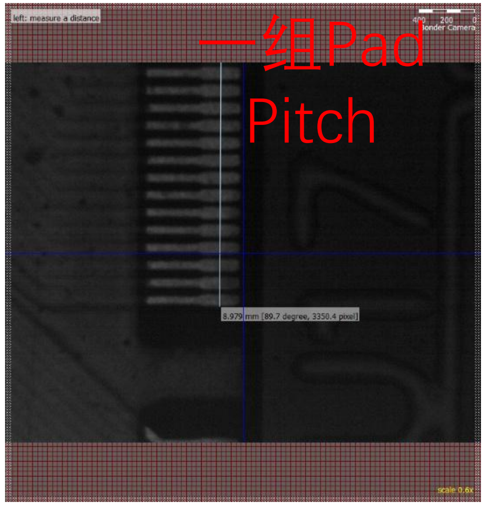
已完成初版程序编写

□FPC Pad与电容Pad不匹配



0.948 mm [90.0 degree, 353.8 pixel]

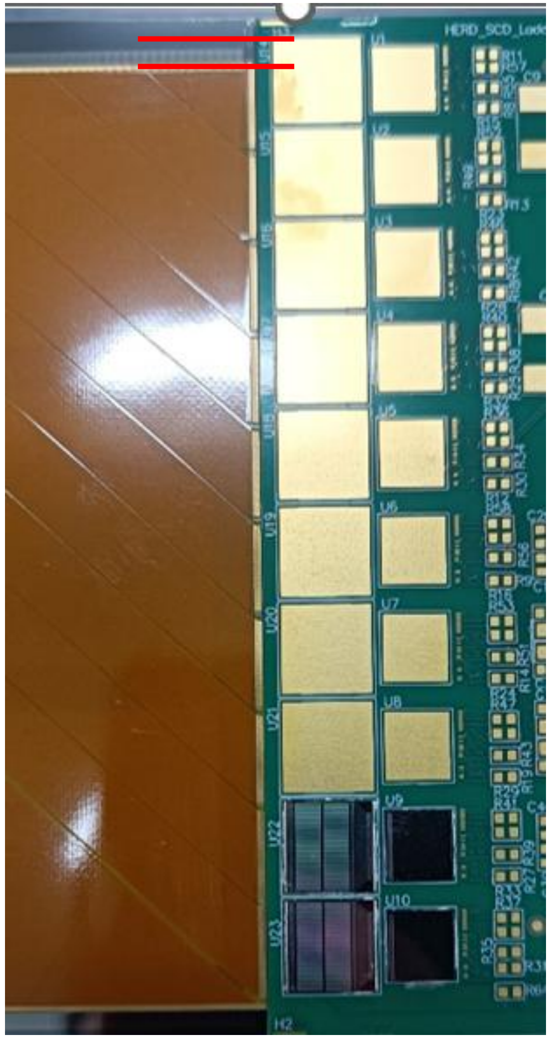
0.747 mm [89.7 degree, 278.7 pixel]

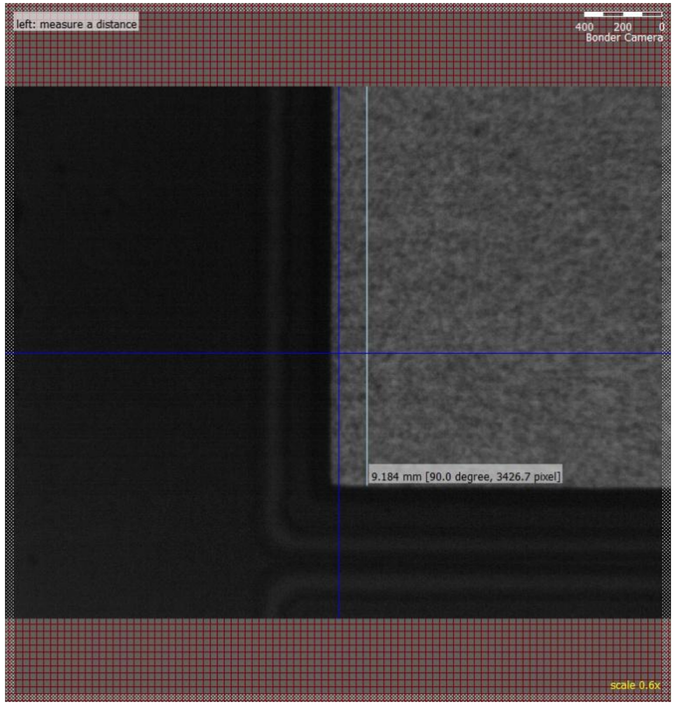


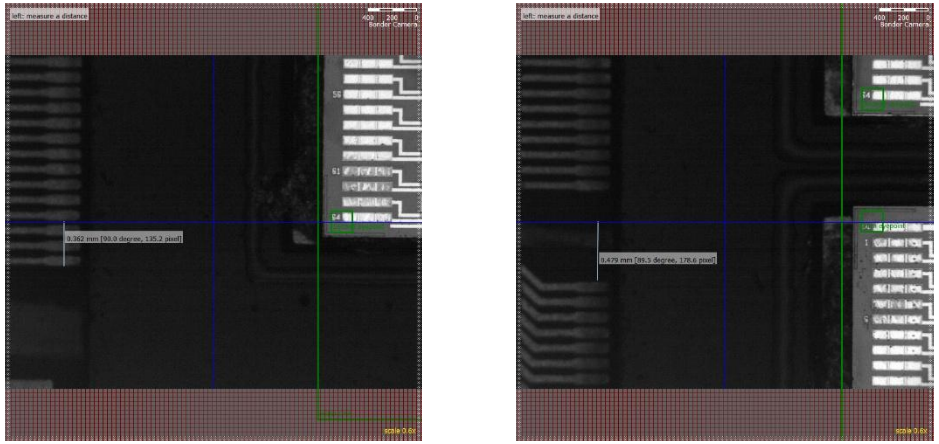
8.979 mm [89.7 degree, 3350.4 pixel]

一组FPC Pad Pitch:
8.980 mm/8.767 mm左右

□FPC粘接精度测量







- 一组电容 Pad Pitch: 9.190mm左右， 相较对应一组FPC Pad宽200+ μm
- 导致最终偏移约2.7 mm
- 十组电容距离PCB两侧距离相差3 mm左右，调整居中可能解决当前问题

Thanks for your attention